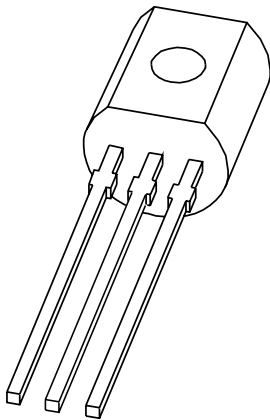


DATA SHEET



PN2907A PNP switching transistor

Product data sheet
Supersedes data of 1997 May 05

2004 Oct 11

PNP switching transistor

PN2907A

FEATURES

- High current (max. 600 mA)
- Low voltage (max. 60 V).

APPLICATIONS

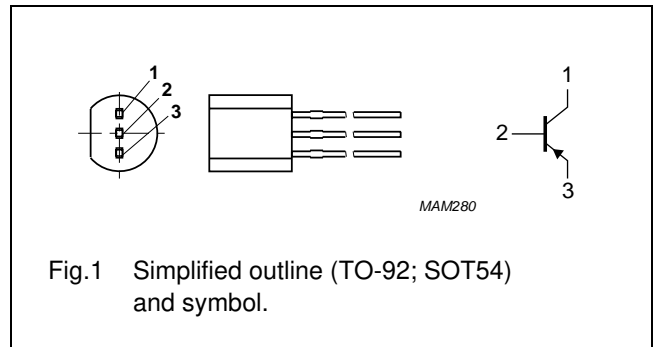
- Switching and linear amplification.

DESCRIPTION

PNP switching transistor in a TO-92; SOT54 plastic package. NPN complement: PN2222A.

PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1 | collector |
| 2 | base |
| 3 | emitter |



QUICK REFERENCE DATA

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|-----------|---------------------------|--|------|------|------|
| V_{CBO} | collector-base voltage | open emitter | – | –60 | V |
| V_{CEO} | collector-emitter voltage | open base | – | –60 | V |
| I_C | collector current (DC) | | – | –600 | mA |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ }^\circ\text{C}$ | – | 500 | mW |
| h_{FE} | DC current gain | $V_{CE} = -10\text{ V}; I_C = -150\text{ mA}$ | 100 | 300 | |
| f_T | transition frequency | $V_{CE} = -20\text{ V}; I_C = -50\text{ mA}; f = 100\text{ MHz}$ | 200 | – | MHz |
| t_{off} | turn-off time | $I_{Con} = -150\text{ mA}; I_{Bon} = -15\text{ mA}; I_{Boff} = 15\text{ mA}$ | – | 365 | ns |

ORDERING INFORMATION

| TYPE NUMBER | PACKAGE | | |
|-------------|---------|---|---------|
| | NAME | DESCRIPTION | VERSION |
| PN2907A | SC-43A | plastic single-ended leaded (through hole) package; 3 leads | SOT54 |

PNP switching transistor

PN2907A

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|-----------|---------------------------|-----------------------------|------|------|------|
| V_{CBO} | collector-base voltage | open emitter | – | –60 | V |
| V_{CEO} | collector-emitter voltage | open base | – | –60 | V |
| V_{EBO} | emitter-base voltage | open collector | – | –5 | V |
| I_C | collector current (DC) | | – | –600 | mA |
| I_{CM} | peak collector current | | – | –800 | mA |
| I_{BM} | peak base current | | – | –200 | mA |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | – | 500 | mW |
| T_{stg} | storage temperature | | –65 | +150 | °C |
| T_j | junction temperature | | – | 150 | °C |
| T_{amb} | ambient temperature | | –65 | +150 | °C |

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---------------|---|------------|-------|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | note 1 | 250 | K/W |

Note

1. Transistor mounted on an FR4 printed-circuit board.

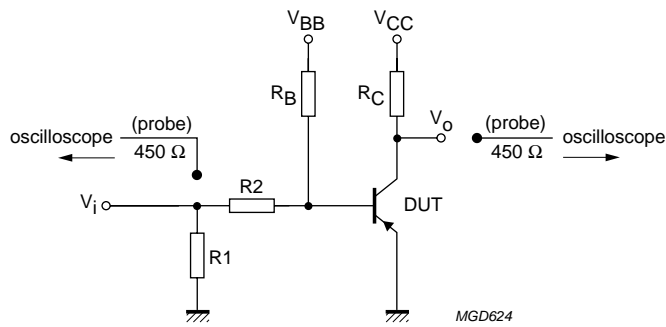
CHARACTERISTICS $T_{amb} = 25\text{ °C}$ unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|-------------|--------------------------------------|---|------|------|---------------|
| I_{CBO} | collector-base cut-off current | $V_{CB} = -50\text{ V}; I_E = 0\text{ A}$ | – | –10 | nA |
| | | $V_{CB} = -50\text{ V}; I_E = 0\text{ A}; T_j = 125\text{ °C}$ | – | –10 | μA |
| I_{EBO} | emitter-base cut-off current | $V_{EB} = -5\text{ V}; I_C = 0\text{ A}$ | – | –50 | nA |
| h_{FE} | DC current gain | $V_{CE} = -10\text{ V}; I_C = -0.1\text{ mA}$ | 75 | – | |
| | | $V_{CE} = -10\text{ V}; I_C = -1\text{ mA}$ | 100 | – | |
| | | $V_{CE} = -10\text{ V}; I_C = -10\text{ mA}$ | 100 | – | |
| | | $V_{CE} = -10\text{ V}; I_C = -150\text{ mA}$ | 100 | 300 | |
| | | $V_{CE} = -10\text{ V}; I_C = -500\text{ mA}$ | 50 | – | |
| V_{CEsat} | collector-emitter saturation voltage | $I_C = -150\text{ mA}; I_B = -15\text{ mA}$ | – | –400 | mV |
| | | $I_C = -500\text{ mA}; I_B = -50\text{ mA}$ | – | –1.6 | V |
| V_{BEsat} | base-emitter saturation voltage | $I_C = -150\text{ mA}; I_B = -15\text{ mA}$ | – | –1.3 | V |
| | | $I_C = -150\text{ mA}; I_B = -50\text{ mA}$ | – | –2.6 | V |
| C_c | collector capacitance | $V_{CB} = -10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$ | – | 8 | pF |
| C_e | emitter capacitance | $V_{EB} = -2\text{ V}; I_C = i_c = 0\text{ A}; f = 1\text{ MHz}$ | – | 30 | pF |
| f_T | transition frequency | $V_{CE} = -20\text{ V}; I_C = -50\text{ mA}; f = 100\text{ MHz}$ | 200 | – | MHz |

PNP switching transistor

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| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|--|---------------|--|------|------|------|
| Switching times (between 10 % and 90 % levels); see Fig.2 | | | | | |
| t_{on} | turn-on time | $I_{Con} = -150 \text{ mA}; I_{Bon} = -15 \text{ mA};$ $I_{Boff} = 15 \text{ mA}$ | – | 40 | ns |
| t_d | delay time | | – | 12 | ns |
| t_r | rise time | | – | 30 | ns |
| t_{off} | turn-off time | | – | 365 | ns |
| t_s | storage time | | – | 300 | ns |
| t_f | fall time | | – | 65 | ns |



$V_i = -9.5 \text{ V}; T = 500 \text{ } \mu\text{s}; t_p = 10 \text{ } \mu\text{s}; t_r = t_f \leq 3 \text{ ns}.$
 $R_1 = 68 \text{ } \Omega; R_2 = 325 \text{ } \Omega; R_B = 325 \text{ } \Omega; R_C = 160 \text{ } \Omega.$
 $V_{BB} = 3.5 \text{ V}; V_{CC} = -29.5 \text{ V}.$
 Oscilloscope: input impedance $Z_i = 50 \text{ } \Omega.$

Fig.2 Test circuit for switching times.

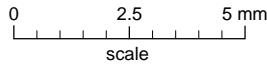
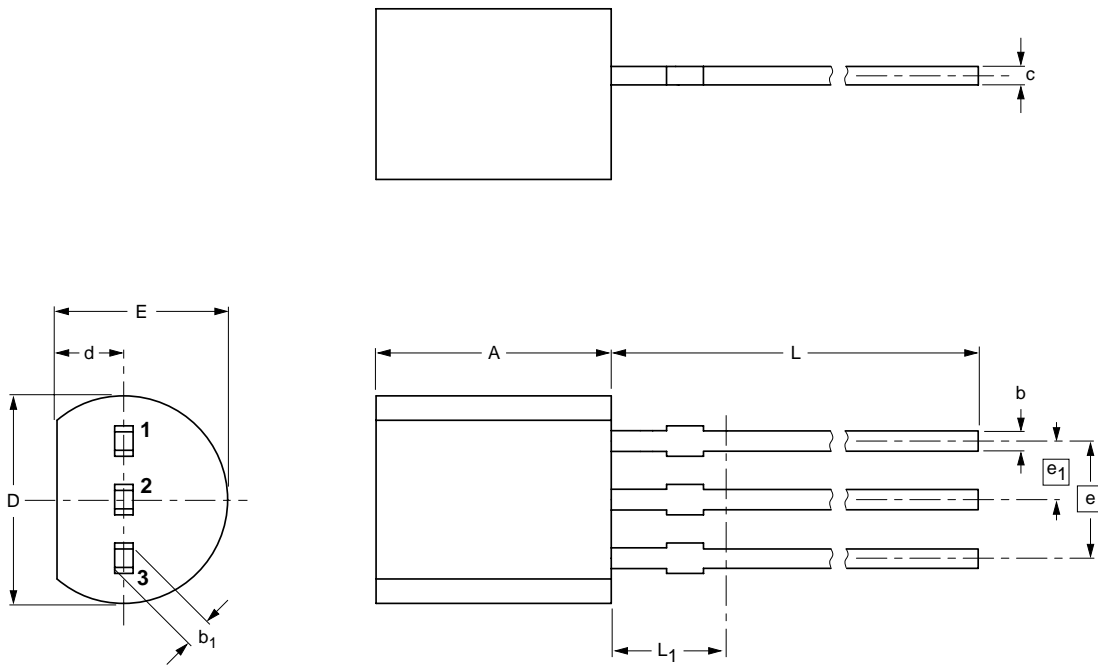
PNP switching transistor

PN2907A

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

| UNIT | A | b | b ₁ | c | D | d | E | e | e ₁ | L | L ₁ ⁽¹⁾ max. |
|------|------------|--------------|----------------|--------------|------------|------------|------------|------|----------------|--------------|---------------------------------------|
| mm | 5.2 5.0 | 0.48 0.40 | 0.66 0.55 | 0.45 0.38 | 4.8 4.4 | 1.7 1.4 | 4.2 3.6 | 2.54 | 1.27 | 14.5 12.7 | 2.5 |

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

| OUTLINE VERSION | REFERENCES | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|--------|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | |
| SOT54 | | TO-92 | SC-43A | | 04-06-28 04-11-16 |

PNP switching transistor

PN2907A

DATA SHEET STATUS

| DOCUMENT STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾ | DEFINITION |
|--------------------------------|-------------------------------|---|
| Objective data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

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Contact information

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